

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-34. canceled

35. (currently amended): An electronic device comprising:

a printed circuit board comprising an electronic component and a grounding portion;

an electromagnetic interference (EMI) EMI-shield comprising ~~an upper~~ a top surface that includes one or more features, a plurality of sidewalls that extend from the top surface, and a flange that extends in a direction substantially parallel to a surface of the printed circuit board; and

a housing of the electronic device configured to enclose the printed circuit board and EMI shield,

wherein the features on the top surface interact with an inner surface of the housing so as to compress the flange of the EMI shield against the grounding portion on the printed circuit board.

36. (original): The electronic device of claim 35 wherein the EMI shield comprise a metallized, shaped polymer substrate.

37. (original): The electronic device of claim 35 wherein the features comprise semi-circular protrusions that extend toward the inner surface of the housing.

38. (original): The electronic device of claim 35 wherein the features are positioned substantially over the sidewalls.

39. (withdrawn): The electronic device of claim 35 wherein the EMI shield further comprises a one or more features that extend from the flange toward the printed circuit

board, and the printed circuit board comprises a corresponding feature that mates with the feature on the EMI shield to locate and retain the EMI shield with the grounding portion.

40. (withdrawn): The electronic device of claim 39 wherein the feature on the flange of the EMI comprises a protrusion and the feature on the printed circuit board comprises a groove.

41. (withdrawn): The electronic device of claim 39 wherein the feature on the printed circuit board is positioned adjacent the grounding portion.

42. (currently amended): An electromagnetic interference (EMI) EMI shield comprising:

a body comprising ~~an upper~~ a top surface that includes one or more features, a plurality of sidewalls that extend from the top surface, and a flange that extends laterally away from the sidewalls; and

wherein the features on the top surface are shaped to interact with an inner surface of a housing of an electronic device when the housing is around the printed circuit board so as to compress the flange of the metallized polymer against a grounding portion on the printed circuit board.

43. (original): The EMI shield of claim 42 wherein the body comprises a metallized polymer.

44. (original): The EMI shield of claim 42 wherein the features comprise semi-circular protrusions that extend in a direction away from the flange.

45. (original): The EMI shield of claim 42 wherein the features are positioned substantially over the sidewalls.

46. (withdrawn): The EMI shield of claim 42 wherein the EMI shield further comprises a one or more features that extend from the flange away from the top surface, the

features on the flange being configured to interact with a corresponding feature to locate and retain the EMI shield with the grounding portion.

47. (withdrawn): The EMI shield of claim 46 wherein the feature on the flange of the EMI comprises a protrusion and the feature on the printed circuit board comprises a groove.

48-54. canceled

55. (new): An electronic device comprising:
a printed circuit board comprising an electronic component and a grounding portion;

an electromagnetic interference (EMI) shield comprising a top surface that includes one or more features, a plurality of sidewalls that extend from the top surface, and a flange that extends in a direction substantially parallel to a surface of the printed circuit board; and

a housing of the electronic device configured to enclose the printed circuit board and EMI shield;

wherein the features on the top surface are dimensionally taller than the available space between the inside of the housing and the printed circuit board; and

wherein the features interact with an inner surface of the housing so as to compress the flange of the EMI shield against the grounding portion on the printed circuit board.

56. (new): The electronic device of claim 55 wherein the features have a convex shape that protrude towards the inner surface of the housing.

57. (new): The electronic device of claim 55 wherein the features are positioned to apply a force downward along the plurality of sidewalls.

58. (new): The electronic device of claim 57 wherein the features are positioned adjacent and above the plurality of sidewalls.

59. (new): The electronic device of claim 55 wherein the features are spaced over the entire top surface.

60. (new): The electronic device of claim 55 further comprising an adhesive applied to the flange so as to position the EMI shield on the grounding portion on the printed circuit board.